

Abstract of the Disclosure

6 A method for forming an extended solder column on a contact pad of
an electronic device comprises steps of (a) applying a solder seed to the
contact pad; (b) contacting the seed with a surface substantially parallel to and
opposite the contact pad, with the seed between the surface and the pad; (c)
melting the seed to wet the contact pad and the surface; (d) extending the
relative separation of the surface and the contact pad, drawing the molten seed
into a column; and (e) solidifying the resultant column. Further in the
invention an integrated circuit (IC) assembly for mounting to a surface of a
device board comprises a plurality of planar ICs interspersed with individual
12 interposers or a or continuous interposer and conductive bars for constraining
the stack and providing conductive paths to the device board.